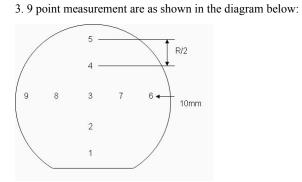
Icemos Technology Ltd Product Specification 1000.678701 Issue Date 15 February 2021 15:

Part Number	Customer
Part Number	Customer

Category	Parameter		Specification	Measurement Method
OverallWafer	1.0	Diameter	150.00 +/- 0.50 mm	
	2.0	Primary Flat Orientation	{110}+/-1 degree	Wafer Vendor
	3.0	Primary Flat Length	57.50 +/- 2.50 mm	Wafer Vendor
	4.0	Overall Thickness	431.00 +/- 10.00 μm	ADE, 100%
	5.0	LPDs > 0.3um	<30	Tencor Particle counter
	6.0	Frontsurface condition	Polished, roughness <5A	Guaranteed by process
	7.0	Total Thickness Variation (TTV)	<5.00μm	Guaranteed by Process
	8.0	Bow	<60.00μm	ADE to ASTM F534, 100%
	9.0	Warp	<60.00μm	
	10.0	Edge Chips	0	Bright Light, 100%
	11.0	Edge Exclusion	5mm	
	12.0	Lasermarking	On wafer BACKSIDE	Guaranteed by process
HandleSilicon	13.0	Handle Growth Method	CZ	Wafer Vendor
	14.0	Handle Orientation	{100} +/- 1 degree	Wafer Vendor
	15.0	Handle Thickness	400.00 +/- 9.00 μm	ADE, 100%
	16.0	Handle Doping Type	P	Wafer Vendor
	17.0	Handle Dopant	Boron	Wafer Vendor
	18.0	Handle Resistivity	8 ~ 12 Ohmcm	Wafer Vendor
	19.0	Backside Finish	Polished with lasermark and oxide	Wafer Vendor
BuriedOxide	20.0	Oxide Type	Thermal	
	21.0	Oxide Thickness	10,000.00 +/- 500.00 A	Nanospec centre point, 4%
	22.0	Oxide formed on	Handle	
DeviceSilicon	23.0	Device Growth Method	CZ	Wafer Vendor
	24.0	Device Orientation	{100} +/- 1 degree	Wafer Vendor
	25.0	Nominal Thickness	30.00 +/- 0.50 μm	Filmetrics, 100% 9-Pt (note3)
	26.0	Distance to device silicon edge from wafer edge	<= 2mm	Typical by Process
	27.0	Device Doping Type	N	Wafer Vendor
	28.0	Device Dopant	Phosphorous	Wafer Vendor
	29.0	Device Resistivity	$3 \sim 7$ ohm-cm	Wafer Vendor
	30.0	Voids	none	IR Inspection, 100%
	31.0	Scratches	0	Bright Light, 100% (note 2)
	32.0	Haze	none	Bright Light, 100% (note 2)
	33.0	Front Surface	Polished, roughness <5A.	Guaranteed by process

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Part Number		Customer			
Category	Parameter	Specification	ı	Me	easurement Method
Shipping Details	Wafer per box :	Max 25			
	Packaging:	Taped Polypropylene Wafer E Empak, Ultrapak, 150.00mm Antistatic Double Bagging	3ox		
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness			
Explanatory Notes	1. Microscope inspe	ction performed using microscope	scan as below. 5x objec	ctive.	
		spections performed exclude all wa	_	•	ed in Overall



Additional Information